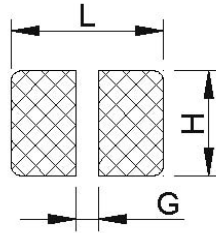


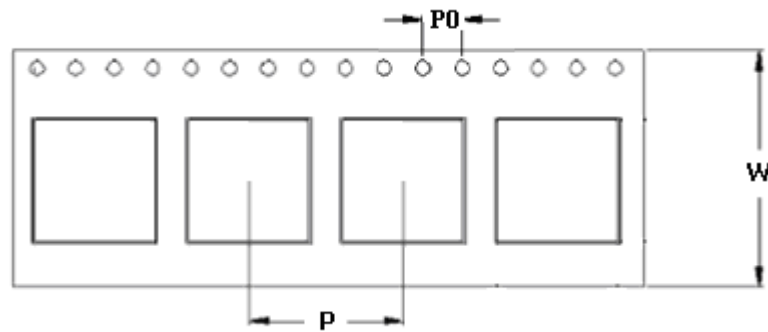
SPECIFICATION FOR APPROVAL

PAD LAYOUT: (UNIT: mm)



ITEM	L (Ref.)	G (Ref.)	H (Ref.)
SPI0603	7.0	4.0	2.2
SPI0703	7.9	4.9	2.2
SPI0705	7.9	4.9	2.2
SPI1005	10.6	5.6	3.2
SPI1206	13.6	8.6	3.2
SPI1207	13.6	8.6	3.2
SPI1208	13.6	8.6	3.2

PACKAGING QUANTITY: (UNIT: mm)



TYPE	P	P0	W	BULK	PCS / REEL
SPI0603	12 ± 0.1	4.0 ± 0.1	16 ± 0.3	v	1000
SPI0703	12 ± 0.1	4.0 ± 0.1	16 ± 0.3	v	1000
SPI0705	12 ± 0.1	4.0 ± 0.1	16 ± 0.3	v	1000
SPI1005	12 ± 0.1	4.0 ± 0.1	24 ± 0.3	v	500
SPI1206	16 ± 0.1	4.0 ± 0.1	24 ± 0.3	v	500
SPI1207	16 ± 0.1	4.0 ± 0.1	24 ± 0.3	v	500
SPI1208	16 ± 0.1	4.0 ± 0.1	24 ± 0.3	v	500

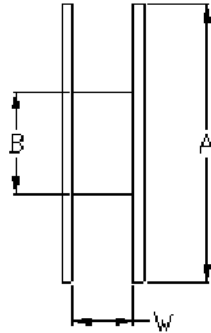
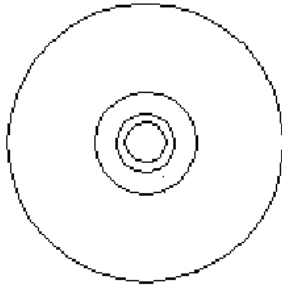
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<http://www.coremaster.com.tw>



SPECIFICATION FOR APPROVAL

PACKAGING QUANTITY: (UNIT: mm)



TYPE	A	B	W
SPI0603	330	100	16.5
SPI0703	330	100	16.5
SPI0705	330	100	16.5
SPI1005	330	100	24.5
SPI1206	330	100	24.5
SPI1207	330	100	24.5
SPI1208	330	100	24.5

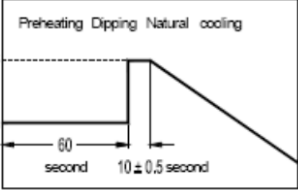
CORE MASTER ENTERPRISE CO., LTD.

<http://www.coremaster.com.tw>



SPECIFICATION FOR APPROVAL

RELIABILITY AND TEST CONDITIONS:

Item	Performance	Test Condition															
Operating Temperature	-40~+125°C																
Rated Current	Refer to standard electrical characteristics list.																
Temperature Rise Test	40°C max. (Δt)																
Solder heat Resistance	Appearance: No significant abnormality. Inductance change: Within $\pm 30\%$.	<p>Preheat: 150°C, 60sec. Solder : H63A Solder temperature: 260+0-5°C Flux: rosin Dip time: 10\pm0.5sec.</p> 															
Thermal shock		<p>Condition for 1 cycle Step1: -25\pm2°C 30\pm3 min. Step2: Room temperature 15 min. Step3: +85\pm5°C 30\pm3 min. Step4: Room temperature 15 min. Number of cycles: 50</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>Phase</th> <th>Temperature(°C)</th> <th>Time(min)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-25\pm2°C</td> <td>30\pm3</td> </tr> <tr> <td>2</td> <td>Room Temp.</td> <td>15</td> </tr> <tr> <td>3</td> <td>+85\pm2°C</td> <td>30\pm3</td> </tr> <tr> <td>4</td> <td>Room Temp.</td> <td>15</td> </tr> </tbody> </table>	Phase	Temperature(°C)	Time(min)	1	-25 \pm 2°C	30 \pm 3	2	Room Temp.	15	3	+85 \pm 2°C	30 \pm 3	4	Room Temp.	15
Phase	Temperature(°C)	Time(min)															
1	-25 \pm 2°C	30 \pm 3															
2	Room Temp.	15															
3	+85 \pm 2°C	30 \pm 3															
4	Room Temp.	15															
Humidity Resistance Test	Appearance: no damage Inductance: within $\pm 30\%$ of initial value.	<p>Measured: 50 times</p> <p>Temperature: 40\pm2°C. Applied current: rated current. Duration: 500 hrs. Humidity: 90~95%</p>															
High Temperature Resistance Test		<p>Temperature: 85\pm2°C. Applied current: rated current. Duration: 500 hrs.</p>															